## Materials Declaration

### Molding Compound

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td>Percentage (%)</td>
<td>PPM</td>
</tr>
<tr>
<td>Other inorganic materials</td>
<td>SiO₂</td>
<td>6037-88-0</td>
<td>8.35 E-04</td>
<td>9.57</td>
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</tr>
<tr>
<td>Thermosets</td>
<td>Phenol Resin</td>
<td>Proprietary</td>
<td>2.68 E-04</td>
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<td>45000</td>
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<tr>
<td>Thermosets</td>
<td>Epoxy Resin 1</td>
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<td>1.79 E-04</td>
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<td>30000</td>
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<tr>
<td>Others</td>
<td>Others</td>
<td>Proprietary</td>
<td>1.19 E-04</td>
<td>2.0</td>
<td>20000</td>
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<tr>
<td>Other inorganic materials</td>
<td>Carbon Black</td>
<td>1333-86-4</td>
<td>1.19 E-05</td>
<td>2.2</td>
<td>2000</td>
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<tr>
<td><strong>Subtotal</strong></td>
<td></td>
<td></td>
<td></td>
<td>1.16 E-03</td>
<td>100%</td>
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### Leadframe

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
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<tbody>
<tr>
<td></td>
<td></td>
<td></td>
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<td>Percentage (%)</td>
<td>PPM</td>
</tr>
<tr>
<td>Copper &amp; its alloys</td>
<td>Copper</td>
<td>7440-50-8</td>
<td>4.43 E-03</td>
<td>97.4</td>
<td>200000</td>
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<tr>
<td>Copper &amp; its alloys</td>
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<td>7430-89-6</td>
<td>1.07 E-04</td>
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<td>230000</td>
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<td>Copper &amp; its alloys</td>
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<td>Copper &amp; its alloys</td>
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### Internal/External Leadframe Plating

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
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</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td>Percentage (%)</td>
<td>PPM</td>
</tr>
<tr>
<td>Copper &amp; its alloys</td>
<td>Copper</td>
<td>7440-50-8</td>
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### Bond Wires

<table>
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<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
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<td>Percentage (%)</td>
<td>PPM</td>
</tr>
<tr>
<td>Precious metals</td>
<td>Gold</td>
<td>7440-57-5</td>
<td>5.00 E-07</td>
<td>1.19</td>
<td>120000</td>
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<td><strong>Subtotal</strong></td>
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<td>100%</td>
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### Die Attach

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
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<tbody>
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<td></td>
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<td>Percentage (%)</td>
<td>PPM</td>
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<tr>
<td>Other inorganic materials</td>
<td>Alumina</td>
<td>1344-38-1</td>
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<td>Other organic materials</td>
<td>Diethylene Glycol Monocryl Ether Acetate</td>
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<td>Thermosets</td>
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<td>Others</td>
<td>Others</td>
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<td>3.00 E-02</td>
<td>100%</td>
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</tbody>
</table>

### Package Totals

<table>
<thead>
<tr>
<th>Description</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>Percentage (%)</td>
<td>PPM</td>
</tr>
<tr>
<td><strong>Package Totals</strong></td>
<td>1.16 E-02</td>
<td>100%</td>
<td>1000000</td>
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</tbody>
</table>

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## Product / Package Information

**Package**  
TSOT  

**Body Size/Pitch**  
5  

**Terminal Finish**  
100 Sn

## Environmental Compliance Information

- **RoHS Compliant**: Yes  
- **High Temperature Compliant**: Yes  
- **Halogen Free Compliant**: Yes  
- **JIG Material Content Compliant**: Level A & B Compliant  
- **REACH SVHC Compliant**: Yes

## Materials Declaration

### Homogeneous Material Level

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Percentage (%)</th>
</tr>
</thead>
<tbody>
<tr>
<td><em>Other inorganic material</em></td>
<td>Silica</td>
<td>7631-86-9</td>
<td>6.20 E-03</td>
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<td>Thermosets</td>
<td>Phenol Resin</td>
<td>Proprietary</td>
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<tr>
<td>Thermosets</td>
<td>Epoxy Resin 1</td>
<td>Proprietary</td>
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<tr>
<td>Thermosets</td>
<td>Epoxy Resin 2</td>
<td>Proprietary</td>
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</tr>
<tr>
<td>Others</td>
<td>Others</td>
<td>Proprietary</td>
<td>1.18 E-04</td>
<td>2.2</td>
</tr>
<tr>
<td>Others</td>
<td>Others</td>
<td>Proprietary</td>
<td>1.18 E-04</td>
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**Subtotal**: 5.96 E-03  
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49  
489858

### Component Level

<table>
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<tr>
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</thead>
<tbody>
<tr>
<td><em>Other inorganic material</em></td>
<td>Silica</td>
<td>1253-86-4</td>
<td>1.18 E-04</td>
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<td>JIG Material Content</td>
<td>Others</td>
<td>Proprietary</td>
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**Subtotal**: 1.22 E-03  
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1000000  
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### Internal Leadframe Plating

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Percentage (%)</th>
</tr>
</thead>
<tbody>
<tr>
<td><em>Copper &amp; its alloys</em></td>
<td>Copper</td>
<td>7439-92-1</td>
<td>6.44 E-03</td>
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<td><em>Copper &amp; its alloys</em></td>
<td>Iron</td>
<td>7439-89-6</td>
<td>1.07 E-04</td>
<td>3.35</td>
</tr>
<tr>
<td><em>Copper &amp; its alloys</em></td>
<td>Zinc</td>
<td>7440-53-9</td>
<td>1.46 E-04</td>
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<tr>
<td><em>Copper &amp; its alloys</em></td>
<td>Phosphorus</td>
<td>13563-38-2</td>
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**Subtotal**: 4.55 E-03  
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37494 |

### External Leadframe Plating

<table>
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<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Percentage (%)</th>
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</thead>
<tbody>
<tr>
<td><em>Precious metals</em></td>
<td>Silver</td>
<td>7440-99-5</td>
<td>6.50 E-04</td>
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### Bond Wires

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Percentage (%)</th>
</tr>
</thead>
<tbody>
<tr>
<td><em>Copper &amp; its alloys</em></td>
<td>Copper</td>
<td>7440-34-4</td>
<td>1.55 E-04</td>
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</table>

**Subtotal**: 1.55 E-04  
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5.89 | 4841 |

### Die

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Percentage (%)</th>
</tr>
</thead>
<tbody>
<tr>
<td><em>Other inorganic material</em></td>
<td>Copper</td>
<td>7440-51-3</td>
<td>0.00 E-04</td>
<td>100</td>
</tr>
</tbody>
</table>

**Subtotal**: 0.00 E-04  
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1000000  
0.00 | 0 |

### Die Attach

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Percentage (%)</th>
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</thead>
<tbody>
<tr>
<td><em>Other inorganic material</em></td>
<td>Doped Silicon</td>
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</table>

**Subtotal**: 8.00 E-04  
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1000000  
0.58 | 5753 |

### Package Totals

**Weight**: 1.22 E-03  
100  
1000000

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